EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	340	257/786.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/10/27 11:25
L3	204	257/773.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:37
L4	20	257/731.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:42
L5	475	257/777.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 12:53
L6	909	257/787.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/10/27 12:53
S3	1114	257/666.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 23:32
S5	626	257/685-686.ccls. and (lead trace wiring pad) with (expos\$3) and (hous\$3 molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 23:32
S6	801	257/777,723.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 00:32
S7	969	257/787,790.ccls. and (lead trace wiring pad) with (expos\$3) and (housing molding mold sealant sealing encapsulating encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:05